Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	4 X 3 X 0.75 (3.3 X 1.7 EP)
Lead Count	14
Terminal Finish	100 Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	1.64E-02	86.2	862000	43.82	438190
Thermosets	Epoxy resin	Proprietary	1.14E-03	6.0	60000	3.05	30500
Thermosets	Phenol resin	Proprietary	1.14E-03	6.0	60000	3.05	30500
Other inorganic materials	Metal Hydroxide	Proprietary	2.85E-04	1.5	15000	0.76	7625
Other inorganic materials	Carbon black	1333-86-4	5.70E-05	0.3	3000	0.15	1525
Subtotal			1.90 E-02	100.00	1000000	50.83	508341

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.42 E-02	97.50	975000	38.09	380854
Copper & its alloys	Iron	7439-89-6	3.43 E-04	2.35	23500	0.92	9180
Copper & its alloys	Zinc	7440-66-6	1.75 E-05	0.12	1200	0.05	469
Copper & its alloys	Phosphorus	7723-14-0	4.38 E-06	0.03	300	0.01	117
Subtotal			1.46 E-02	100.00	1000000	39.06	390620

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	3.65 E-05	100.0	1000000	0.10	977

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	8.00 E-04	100.0	1000000	2.14	21404

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	4.00 E-05	100.0	1000000	0.11	1070

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.70 E-03	100.0	1000000	7.22	72238

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.55 E-04	77.71	777100	0.42	4158
Thermoset	Epichlorohydrin-formaldehyde-phenol copolymer	9003-36-5	6.22 E-06	3.11	31100	0.02	166
Other organic materials	Epoxy resin, epichlorohydrin-dimer fatty acid	68475-94-5	6.22 E-06	3.11	31100	0.02	166
Other organic materials	Butyrolactone, gamma-	96-48-0	6.22 E-06	3.11	31100	0.02	166
Other organic materials	Poly(oxypropylene)diamine	9046-10-0	6.22 E-06	3.11	31100	0.02	166
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	6.22 E-06	3.11	31100	0.02	166
Other organic materials	Organosilane	TS ref# 10001	6.22 E-06	3.11	31100	0.02	166
Other inorganic materials	Copper(II) oxide	1317-38-0	6.22 E-06	3.11	31100	0.02	166
Other organic materials	Epoxy resin modifier	TS ref# 10038	1.04 E-06	0.52	5200	0.003	28
Subtotal			2.00 E-04	100.0	1000000	0.54	5351

	Weight (g)	Percentage (%)	PPM
Package Totals	**3.74 E-02**	100	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES

ADI Proprietary